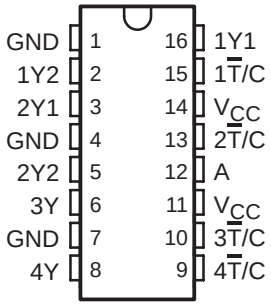
- **Low Output Skew for Clock-Distribution and Clock-Generation Applications**
- **TTL-Compatible Inputs and Outputs**
- **Distributes One Clock Input to Six Clock Outputs**
- **Polarity Control Selects True or Complementary Outputs**
- **Distributed V_{CC} and GND Pins Reduce Switching Noise**
- **High-Drive Outputs (−48-mA I_{OH}, 48-mA I_{OL})**
- **State-of-the-Art *EPIC*-II*B* ™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Package Options Include Plastic Small-Outline (D) and Shrink Small-Outline (DB) Packages**

D OR DB PACKAGE
(TOP VIEW)



description

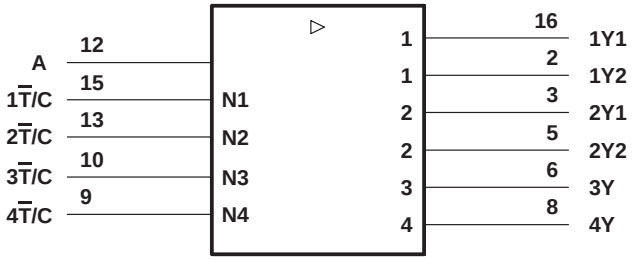
The CDC328A contains a clock-driver circuit that distributes one input signal to six outputs with minimum skew for clock distribution. Through the use of the polarity-control inputs ($\overline{T}$/C), various combinations of true and complementary outputs can be obtained.

The CDC328A is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

INPUTS		OUTPUT
$\overline{T}$/C	A	Y
L	L	L
L	H	H
H	L	H
H	H	L

logic symbol†

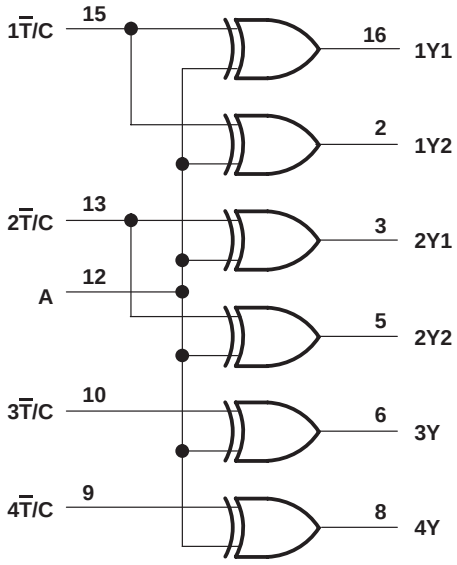


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 7 V
Voltage range applied to any output in the high state
or power-off state, V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Current into any output in the low state, I_O . . . . . 96 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . −18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . −50 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): D package . . . . . 0.77 W
DB package . . . . . 0.6 W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
I_{OH}	High-level output current			−48	mA
I_{OL}	Low-level output current			48	mA
$\Delta t/\Delta v$	Input transition rise or fall rate			5	ns/V
f_{clock}	Input clock frequency			100	MHz
T_A	Operating free-air temperature	−40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

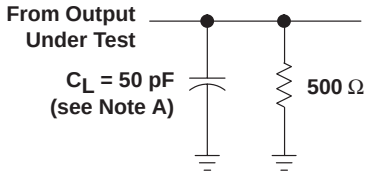
PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}	V_{CC} = 4.75 V,	I_I = −18 mA				−1.2	V
V_{OH}	V_{CC} = 4.75 V,	I_{OH} = −48 mA		2			V
V_{OL}	V_{CC} = 4.75 V,	I_{OL} = 48 mA				0.5	V
I_I	V_{CC} = 5.25 V,	V_I = V_{CC} or GND				±1	μA
I_O‡	V_{CC} = 5.25 V,	V_O = 2.5 V		−15		−100	mA
I_{CC}	V_{CC} = 5.25 V, V_I = V_{CC} or GND	I_O = 0,	Outputs high			10	mA
			Outputs low			40	
C_i	V_I = 2.5 V or 0.5 V				3		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

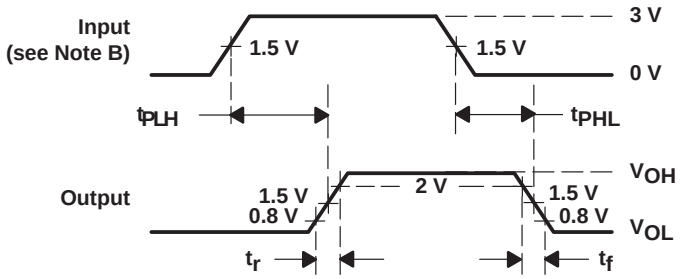
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t_{PLH}	A	Any Y	1.7	5	ns
t_{PHL}			1.5	5	
t_{PLH}	$\overline{T}$/C	Any Y	1.5	5	ns
t_{PHL}			1.4	5	
$t_{sk(o)}$	A	Any Y (same phase)		0.5	ns
		Any Y (any phase)		1	
$t_{sk(p)}$	A	Any Y		1	ns
t_r		Any Y		1.5	ns
t_f		Any Y		1.5	ns

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR OUTPUTS

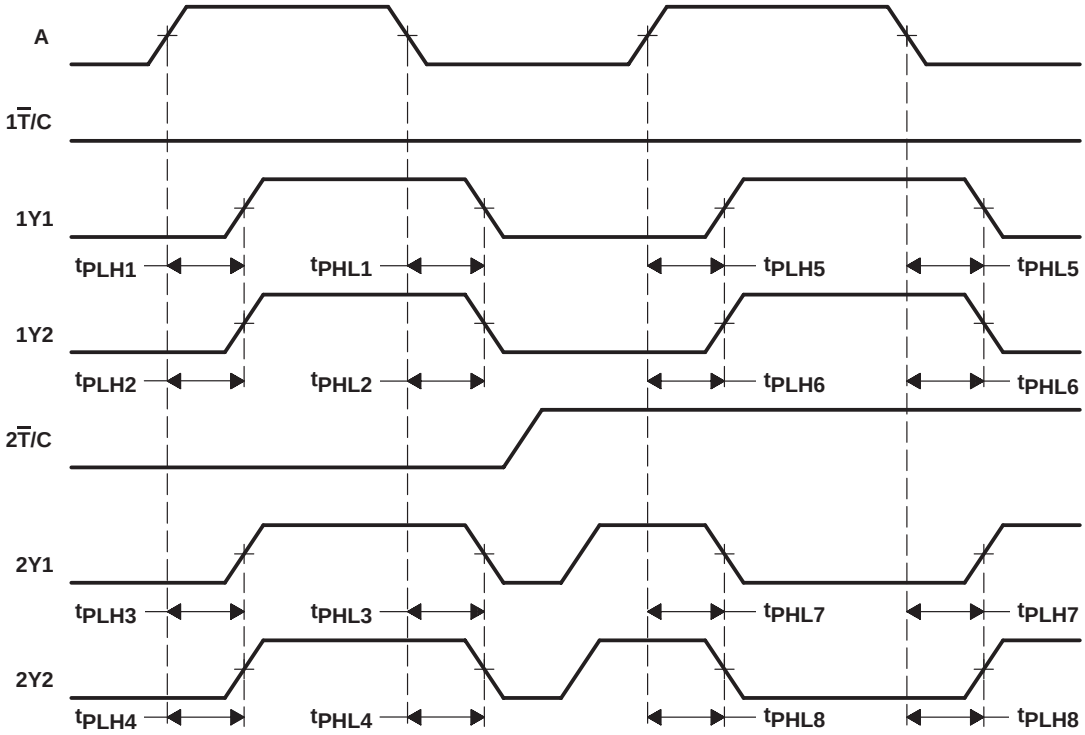


VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. Output skew, $t_{sk(o)}$, from A to any Y (same phase), can be measured only between outputs for which the respective polarity-control inputs ($\overline{T}$/C) are at the same logic level. It is calculated as the greater of:
- The difference between the fastest and slowest of t_{PLH} from A↑ to any Y (e.g., t_{PLHn}, n = 1 to 4; or t_{PLHn}, n = 5 to 6)
- The difference between the fastest and slowest of t_{PHL} from A↓ to any Y (e.g., t_{PHLn}, n = 1 to 4; or t_{PHLn}, n = 5 to 6)
- The difference between the fastest and slowest of t_{PLH} from A↓ to any Y (e.g., t_{PLHn}, n = 7 to 8)
- The difference between the fastest and slowest of t_{PHL} from A↑ to any Y (e.g., t_{PHLn}, n = 7 to 8)

B. Output skew, $t_{sk(o)}$, from A to any Y (any phase), can be measured between outputs for which the respective polarity-control inputs ($\overline{T}$/C) are at the same or different logic levels. It is calculated as the greater of:
- The difference between the fastest and slowest of t_{PLH} from A↑ to any Y or t_{PHL} from A↑ to any Y (e.g., t_{PLHn}, n = 1 to 4; or t_{PLHn}, n = 5 to 6, and t_{PHLn}, n = 7 to 8)
- The difference between the fastest and slowest of t_{PHL} from A↓ to any Y or t_{PLH} from A↓ to any Y (e.g., t_{PHLn}, n = 1 to 4; or t_{PHLn}, n = 5 to 6, and t_{PLHn}, n = 7 to 8)

C. Pulse skew, $t_{sk(p)}$, is calculated as the greater of $|t_{PLHn} - t_{PHLn}|$(n = 1, 2, 3, 4, 5, 6 ,7, 8).

Figure 2. Waveforms for Calculation of $t_{sk(o)}$, $t_{sk(p)}$

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CDC328AD	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A
CDC328AD.B	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A
CDC328ADBR	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CK328A
CDC328ADBR.B	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CK328A
CDC328ADG4	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A
CDC328ADR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A
CDC328ADR.B	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A
CDC328ADRG4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A
CDC328ADRG4.B	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDC328A

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

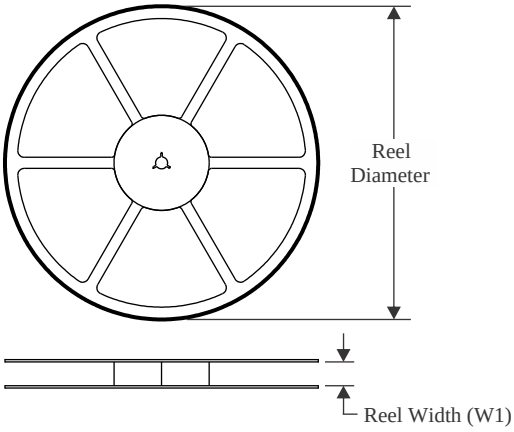
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative

and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

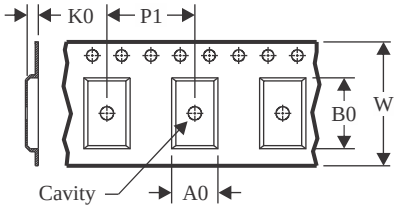
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

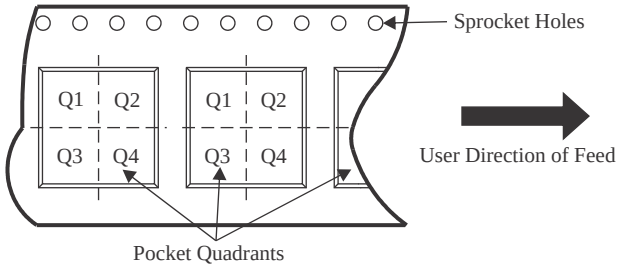


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

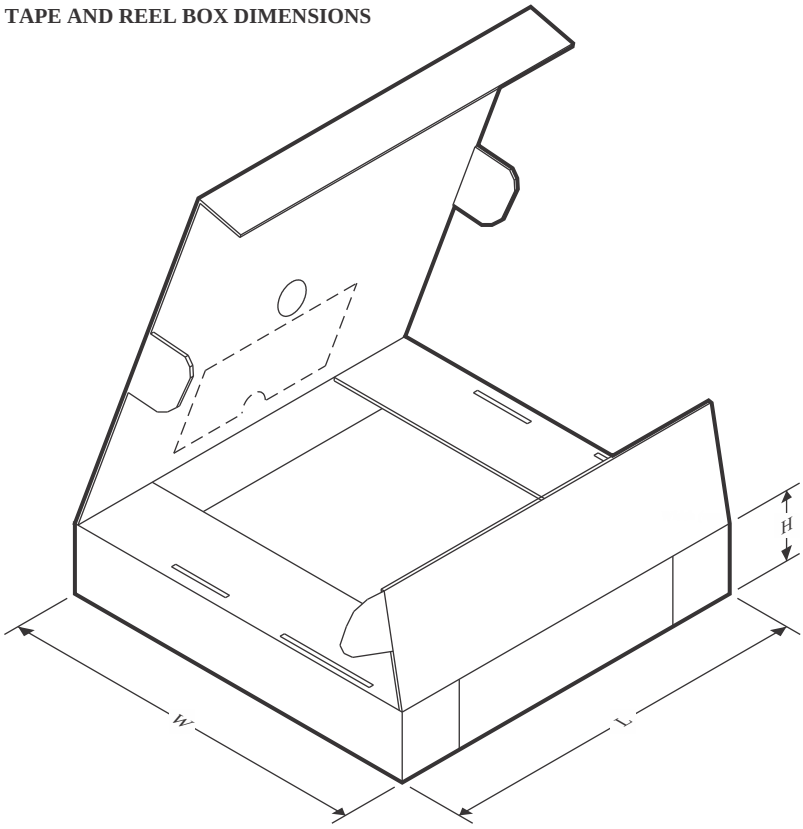
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC328ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
CDC328ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CDC328ADRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

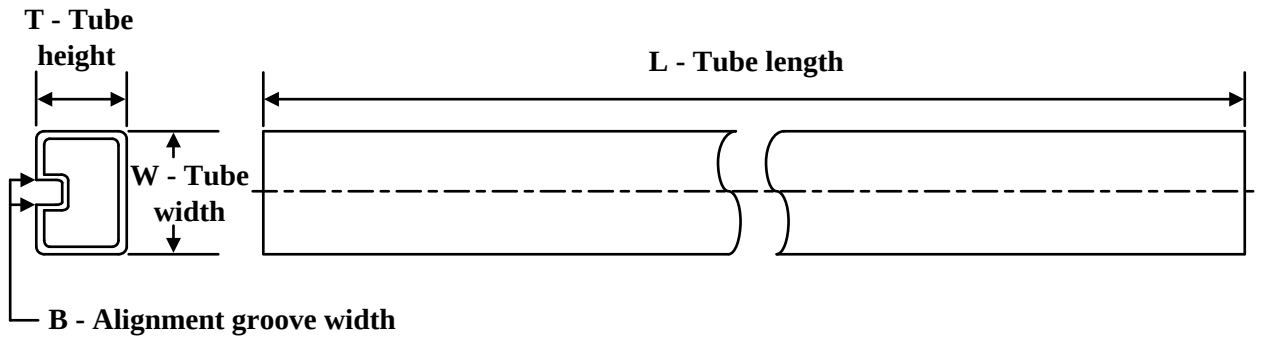
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC328ADBR	SSOP	DB	16	2000	353.0	353.0	32.0
CDC328ADR	SOIC	D	16	2500	350.0	350.0	43.0
CDC328ADRG4	SOIC	D	16	2500	350.0	350.0	43.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CDC328AD	D	SOIC	16	40	505.46	6.76	3810	4
CDC328AD.B	D	SOIC	16	40	505.46	6.76	3810	4
CDC328ADG4	D	SOIC	16	40	505.46	6.76	3810	4

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265